

Bump-Bonding/Thinning

- Contact, possible collaboration, Simon Kwan FNAL, BTEV
- Developing plan
 - 2003 small scale participation, learning curve
 - 2004 trials of leading candidates for phenix chips
 - who is interested, CO, others?
- Two leading companies
 - MCNC (Development) / Unitive (commercial) Nth. Car.
 - » bump-first then thin
 - » so far no success
 - AIT Advanced Interconnect Technologies (Hong Kong)
 - » thin first then bump
 - » success with 150micron 4" wafers

